

## Application Data Sheet

### Application Information

Application Type:: Regular  
Subject Matter:: Utility  
Title:: Raised Solder-Mask-Defined (SMD)  
Solder Ball Pads For A Laminate  
Electronic Circuit Board  
Attorney Docket Number:: TI-36052 (1962-07500)  
Request for Early Publication?:: No  
Request for Non-Publication?:: No  
Suggested Drawing Figure:: 1  
Total Drawing Sheets:: 7  
Small Entity?:: No

### Applicant Information

Applicant Authority type:: Inventor  
Primary Citizenship Country:: Taiwan  
Status:: Full Capacity  
Given Name:: Tz-Cheng  
Family Name:: CHIU  
City of Residence:: Plano  
State or Province of Residence:: TX  
Country of Residence:: US  
Street of mailing address:: 3620 Dripping Springs Drive  
City of mailing address:: Plano  
State or Province of  
mailing address:: TX  
Country of mailing address:: US  
Postal or Zip Code of  
mailing address:: 75025  
  
Applicant Authority type:: Inventor

Primary Citizenship Country:: India  
Status:: Full Capacity  
Given Name:: Manjula N.  
Family Name:: VARIYAM  
City of Residence:: Plano  
State or Province of Residence:: TX  
Country of Residence:: US  
Street of mailing address:: 2117 Country Club Drive  
City of mailing address:: Plano  
State or Province of  
mailing address:: TX  
Country of mailing address:: US  
Postal or Zip Code of  
mailing address:: 75074

**Correspondence Information**

Correspondence Customer Number:: 23494

**Representative Information**

Representative Customer Number:: 23494

**Assignee Information**

Assignee name:: Texas Instruments Incorporated  
Street of mailing address:: P.O. Box 655474, MS 3999  
City of mailing address:: Dallas  
State or Province of  
mailing address:: TX  
Country of mailing  
address:: US  
Postal or Zip Code of  
mailing address:: 75265